



# SPECIFICATION FOR COLOR STN LCD MODULE

# MODEL NO: <u>TM128128CKFWG32-9</u> CUSTOMER:<u>w w w . F i n d L C D . </u>c o m

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PREPARED	CHECKED	VERIFIED BY R&D DEPT	VERIFIED BY QC DEPT	APPROVED

### **REVISION RECORD**

Date	Rev.No.	Revision Items	Prepared	Checked	Approved
2006.2.8	V1.0	NEW			

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### **1.General Specifications**

Item	Contents	Unit	Note
LCD Type	Color STN	-	
Display color	65K		1
LCD Duty	1/128	-	
LCD Bias	1/5	-	
Viewing Direction	6:00	O'Clock	
Viewing Area(W×H)	28.3×30.17	mm	
Active Area(W×H)	26.1×28.15	mm	
Number of Dots	128(RGB)×128	mm	
Dote Size(W×H)	0.192×0.210	mm	
Dot Pitch(W×H)	0.204×0.220	mm	
Controller	S6B33B6	-	
V <sub>DD</sub>	3.0	V	
Vop	10.6	V	
Outline Dimensions	Refer to outline drawing on next page		
Backlight	LED(white)	-	
Operating Temperature	<b>-20∼+70</b> °C	-	
Storage Temperature	<b>-30∼+80</b> ℃	-	
Weight	TBD	g	2
Data Transfer	16 bits parallel	-	
Polarizer Mode	Transmissive/Negative	-	

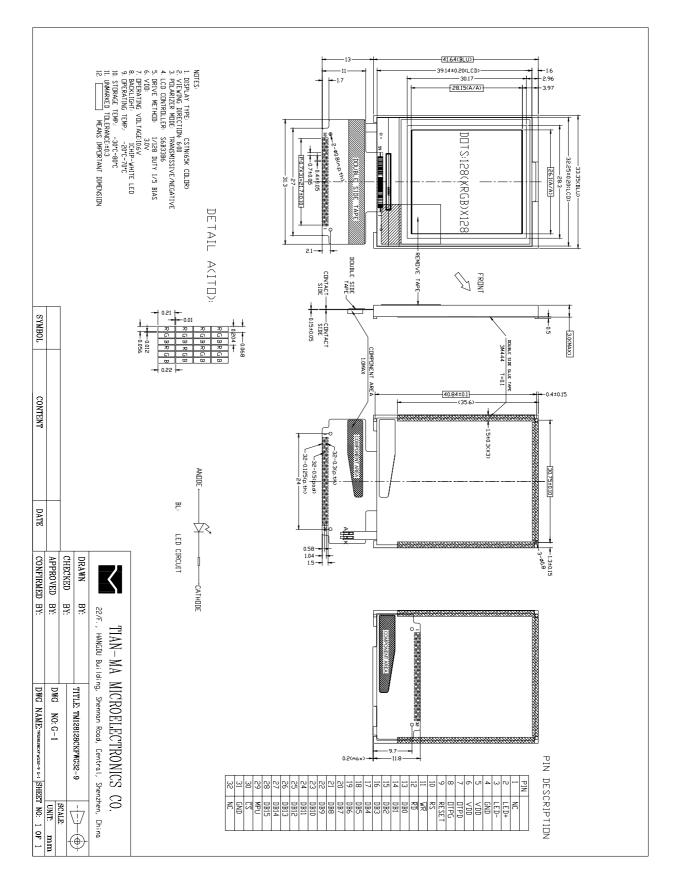
Note 1: Color tune is slightly changed by temperature and driving voltage.

Note 2: TBD- To Be Determined.

Note: Requirements on Environmental Protection:RoHS

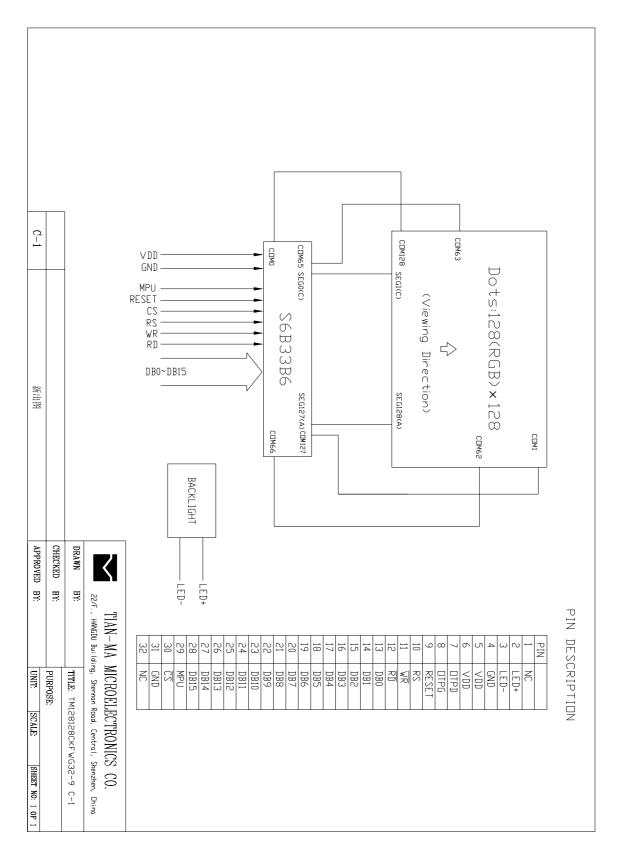


### 2. Outline Drawing





### 3. Circuit Block Diagram





### 4. Absolute Maximum Ratings(Ta=25 °C)

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	$V_{DD}$	-0.3	3.3	V	
Power Supply Voltage for LCD	Vop	-	12	V	
Logic Signal Input Voltage	$V_{I}$	-0.3	V <sub>DD</sub> +0.3	V	
Operating Temperature	Тор	-20	+70	°C	
Storage Temperature	Tst	-30	+80	°C	

Notes:

- 1. If the module is above these absolute maximum ratings. It may become permanently damaged. Using the module within the following electrical characteristic conditions are also exceeded, the module will malfunction and cause poor reliability.
- 2.  $V_{DD} > V_{SS}$  must be maintained.



### **5. Electrical Specifications and Instruction Code**

### 5.1 Electrical characteristics (Ta=25 °C)

Paran	neter	Symbol	Condition	Min	Тур	Max	Unit	Note
Opera volta		V <sub>OP</sub>	Ta=25 ℃	10.3	10.6	10.9	V	1
Input	'H'	$V_{\mathrm{IH}}$	V <sub>DD</sub> =3.0V	$0.8V_{DD}$	-	V <sub>DD</sub>	V	
voltage 'L'	ʻL'	V <sub>IL</sub>	V <sub>DD</sub> =3.0V	Vss	-	0.2V <sub>D</sub>	V	
Output	'H'	$V_{OH}$	-	$0.8V_{DD}$	-	$\mathbf{V}_{\mathrm{DD}}$	V	
Voltag e 'L'		V <sub>OL</sub>	-	Vss	-	0.2V <sub>D</sub>	V	
Current		I <sub>CC1</sub>	Normal mode	-	22	30	mA	2
Consur	nption	I <sub>CC2</sub>	Stand-by mode	-	-	-	mA	3

Note:

- 1: IC default setting, Duty:1/128,Bias:1/5.
- 2: Display full white. Backlight on state.
- 3: IC on standby mode.



### 5.2 LED backlight specification

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Ite	Item		Condition	Min	Тур	Max	Unit	Note
Forward	l voltage	$V_{\mathrm{f}}$	I <sub>f</sub> =20mA		3.6		V	
Reverse	Reverse voltage					4	V	
Forward	Normal	I <sub>pn</sub>	1 shin		20		A	
current	Dimming	I <sub>pd</sub>	1-chip		20		mA	
Reverse Current		I <sub>r</sub>	V <sub>r</sub> =4V			15	μΑ	
Unifo	ormity		I <sub>f</sub> =20mA	80%				



### 5.3 Interface Signals

Pin No.	Symbol	Function
1	NC	Dummy
2	LED+	Back light+
3	LED-	Back light -
4	GND	Ground
5	VDD	Power supply
6	VDD	Power supply
7	OTPD	OTP pin
8	OTPG	OTP pin
9	RESET	Reset input pin.
10	RS	Data/instruction select input pin
11	WR	Write execution control pin
12	RD	Read execution control pin
13	D0	
14	D1	
15	D2	
16	D3	
17	D4	
18	D5	
19	D6	
20	D7	Data bus
21	D8	Data ous
22	D9	
23	D10	
24	D11	
25	D12	
26	D13	
27	D14	
28	D15	
29	MPU	MPU interface select pin(L 8080, H 6800)
30	CS	Chip select pin
31	GND	Ground
32	NC	Dummy



#### **5.4 Interface Timing Chart**

Note: Please refer to SAMSUNG's S6B33B6 data sheet for more details.

#### SAMSUNG S6B33B6 INTERFACE PROTOCOL

#### Read/Write Characteristics (8080-series MPU)

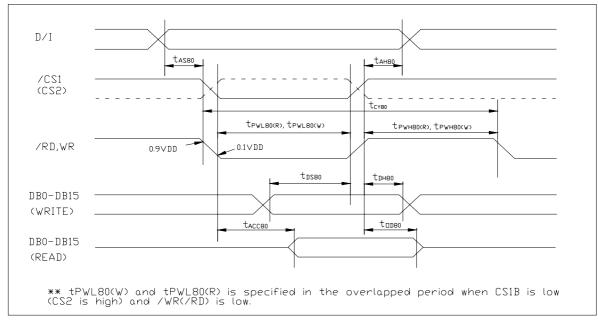


Figure. Parallel Interface (8080-series MPU) Timing Diagram

Table. AC Characteristics(8080-series parallel Mode) (V<sub>DD3</sub>=1.8∼3.3V,Ta=-30~+70 °C)

Item	Signal	Symbol	Condition	Μ	in.	Max.	Unit
Itelli	Signal	Symbol	Condition	3.3V	1.8V	(3.3V/1.8V)	/1.8V) Unit ns ns ns ns ns ns
Address setup time	D/I	$t_{AS80}$		0	0		20
Address hold time	D/1	$t_{\rm AH80}$		0	0	-	115
System cycle time		$t_{\rm CY80}$		150	360	-	ns
Pulse width low for write	WRB	$t_{\rm PWLW}$		50	100		120
Pulse width high for write	(WRB)	$t_{\rm PWHW}$		100	75	-	115
Pulse width low for read	RDB	t <sub>PWLR</sub>		50	100		nc
Pulse width high for read	(RDB)	$t_{\rm PWHR}$		30	75	-	115
Data setup time	DB0	$t_{\rm DS80}$		5	10		nc
Data hold time	to	$t_{\rm DH80}$		8	14	-	115
Read access time	DB15	t <sub>ACC80</sub>	CL=100pF		-	60/120	ns
Output disable time		$t_{\rm OD80}$	CL-100pl		t <sub>EWH</sub>	R	ns

NOTE\*1. The intput signal rise time and fall time(tr,tf) is specified at 10 ns or less.

(tr+tf)<(t<sub>CY80</sub>-t<sub>PWLW</sub>-t<sub>PWHW</sub>) for write, (tr+tf)<(t<sub>CY80</sub>-t<sub>PWLR</sub>-t<sub>PWHR</sub>) for read.



#### INSTRUCTION DESCRIPTION

				Instru	iction	Tabl	e							
Instruction Name	D⁄I	WRB	RDB	DB15 ~ <sup>DB8</sup>	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Hex	Paramete
Non Operation	0	0	1	*	0	0	0	0	0	0	0	0	00	
Oscillation Mode Set	0	0	1	*	0	0	0	0	0	0	1	0	02	1Byte
Driver Output Mode Set	0	0	1	*	0	0	0	1	0	0	0	0	10	1Byte
DC-DC Select	0	0	1	*	0	0	1	0	0	0	0	0	20	1Byte
Bias Set	0	0	1	*	0	0	1	0	0	0	1	0	22	1Byte
DCDC Clock Division Set	0	0	1	*	0	0	1	0	0	1	0	0	24	1Byte
DCDC and AMP ON/OFF Set	0	0	1	*	0	0	1	0	0	1	1	0	26	1Byte
emperature Compensation Set	0	0	1	*	0	0	1	0	1	0	0	0	28	1Byte
Contrast Control(1)	0	0	1	*	0	0	1	0	1	0	1	0	2A	1Byte
Contrast Control(2)	0	0	1	*	0	0	1	0	1	0	1	1	2B	1Byte
Standby Mode OFF	0	0	1	*	0	0	1	0	1	1	0	0	2C	-
Standby Mode ON	0	0	1	*	0	0	1	0	1	1	0	1	2D	-
DDRAM Burst Mode OFF	0	0	1	*	0	0	1	0	1	1	1	0	2E	-
DDRAM Burst Mode ON	0	0	1	*	0	0	1	0	1	1	1	1	2F	-
Addressing Mode Set	0	0	1	*	0	0	1	1	0	0	0	0	30	1Byte
ROW Vector Mode Set	0	0	1	*	0	0	1	1	0	0	1	0	32	1Byte
N-line Inversion Set	0	0	1	*	0	0	1	1	0	1	0	0	34	1Byte
Entry Mode Se	0	0	1	*	0	1	0	0	0	0	0	0	40	1Byte
X-address Area Set	0	0	1	*	0	1	0	0	0	0	1	0	42	1Byte
Y-address Area Set	0	0	1	*	0	1	0	0	0	0	1	1	43	1Byte
RAM Skip Area Set	0	0	1	*	0	1	0	0	0	1	0	1	45	-
Display OFF	0	0	1	*	0	1	0	1	0	0	0	0	50	-
Display ON	0	0	1	*	0	1	0	1	0	0	0	1	51	-
Specified Display Pattern Set	0	0	1	*	0	1	0	1	0	0	1	1	53	1Byte
Partial Display Mode Set	0	0	1	*	0	1	0	1	0	1	0	1	55	1Byte
Partial Display Start Line Set	0	0	1	*	0	1	0	1	0	1	1	0	56	1Byte
Partial Display End Line Set	0	0	1	*	0	1	0	1	0	1	1	1	57	1Byte
Area Scroll Mode Set	0	0	1	*	0	1	0	1	1	0	0	1	59	1Byte
Scroll Start Line Set	0	0	1	*	0	1	0	1	1	0	1	0	5A	1Byte
Scroll Start Line Set	Х	Х	Х	*	1	1	1	1	1	1	0	0	FC	1Byte
Display Data Write	1	0	1				Display	y Data V	Write				-	-
Display Data Read	1	1	0			]	Display	Data R	ead *				-	-
Status Read	0	1	0	0					Data Rea	d			-	-
Test Mode1	0	0	1	*	1	1	1	1	1	1	1	1	FF	-
Test Mode2	0	0	1	*	1	1	1	1	1	1	1	0	FE	-
Test Mode3	0	0	1	*	1	1	1	1	1	1	0	1	FD	-
Test Mode4	0	0	1	*	1	1	1	1	1	0	1	1	FB	-
Test Mode5	0	0	1	*	1	1	1	1	1	0	1	0	FA	-
Test Mode6	0	0	1	*	1	1	1	1	1	0	0	1	F9	-

\*: Don't care

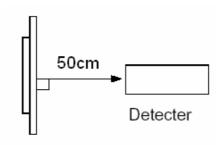


## 6. Optical Characteristics

Item	Sy	ymbol	Condition	Min.	Тур.	Max.	Unit	Note
Brightness		Вр	Ф1=0°	80			Cd/m <sup>2</sup>	1
Uniformity	2	∆Bp	Ф2=0°	70%				1,2
Viewing	$\Phi_1(u)$	p down)	Cr≥2	-	40~+35		Dec	2
Angle	$\Phi_2(le$	eft right)	CI≥2	-	-30~+30		Deg	3
Contrast Ratio		Cr	Φ <sub>1</sub> =0°	30	40	60	-	4
Response		Tr	$\Phi_1=0$ $\Phi_2=0^{\circ}$	I	-	180	ms	5
Time	T <sub>f</sub>			70	-	90		5
	W	х	-	I	0.30	-	-	
	vv	у		-	0.36	-	-	
	R	х		I	0.53	-	-	
Color of CIE	K	у		-	0.37	-	-	
Coordinate	G	х	$\Phi_1=0^{\circ} \Phi_2=0^{\circ}$	-	0.31	-	-	1,6
	U	у	2	-	0.51	-	-	
	В	х		-	0.16	-	-	
	У			-	0.18	-	-	
NTSC Ratio		S			25%			



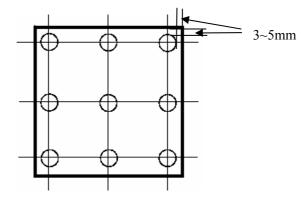
Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment PR-705 (Φ10mm)



Note 2:  $\triangle Bp = Bp (Min.) / Bp (Max.) \times 100 (\%)$ 

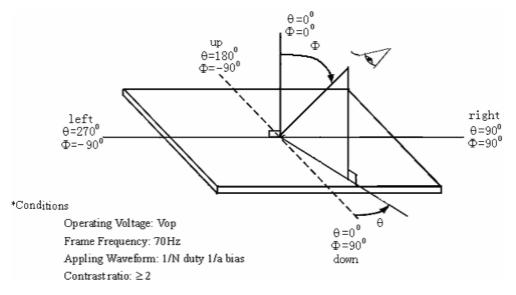
Bp (Max.) = Maximum brightness in 9 measured spots

Bp (Min.) = Minimum brightness in 9 measured spots.



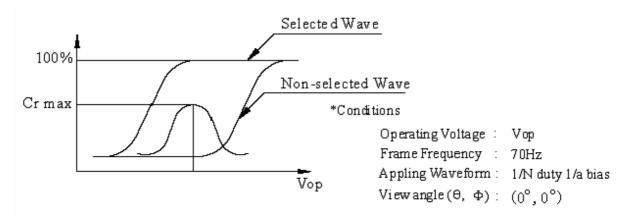
Measurement equipment PR-705 (Φ10mm)

Note 3: Definition of Viewing Angle(Test LCD using DMS501)



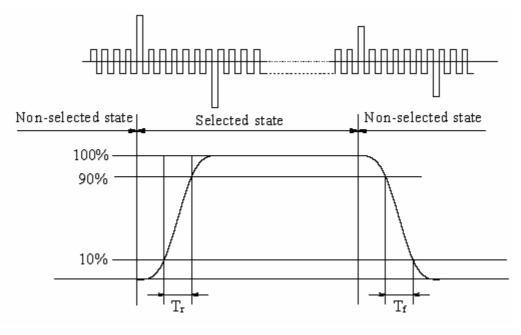


Note 4: Definition of contrast ratio.( Test LCD using DMS501)



Contrast ratio(Cr) =  $\frac{Brightness of selected dots}{Brightness of non-selected dots}$ 

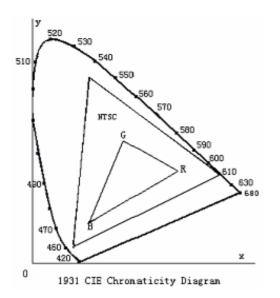
Note 5: Definition of Response time(Test LCD using DMS501)



Operating Voltage: Vop Frame Frequency: 70Hz Appling Waveform: 1/N duty 1/a bias View angle  $(\theta, \Phi)$ :  $(0^0, 0^0)$ 



Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.



Color gamut:

 $S = \frac{area \ of \ RGB \ triangle}{area \ of \ NTSC \ triangle} \times 100\%$ 



## 7. Reliability

E.

No.	Test Item	Test condition	Criterion
1	High Temperature Storage	80℃±2℃96H Restore 4H at 25℃	
2	Low Temperature Storage	-30℃±2℃ 96H Restore 4H at 25℃	
3	High Temperature Operation	70℃±2℃ 48H Restore 4H at 25℃	
4	Low Temperature Operation	-20℃±2℃ 48H Restore 4H at 25℃	1. After testing, cosmetic
5	High Temperature /Humidity Storage	40℃±2℃ 90%RH 48H	defects should not happen. 2.Total current consumption should not be over 10% of
6	Temperature Cycle	$-30^{\circ}C \longleftrightarrow 25^{\circ}C \longleftrightarrow 80^{\circ}C$ 5min 30min $\longleftrightarrow 25^{\circ}C,$ 5min after 10cycle, Restore 4H at 25^{\circ}C	initial value.
7	Vibration Test (package state)	10Hz~150Hz, 100m/s2, 120min	
8	Shock Test (package state)	Half- sine wave, 300m/s2, 18ms	Not allowed cosmetic and electrical defects.
9	Atmospheric Pressure Test	25kPa 16H Restore 2H	
10	Cable Bending Test	Bending area and angle follow design document requirement	More than 50000 times



## 8 Quality level

### 8.1 Notes for quality standard

	Note			
General	<ol> <li>Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and Tianma.</li> <li>Viewing Area should be the area which Tianma guarantees.</li> <li>Limited sample should be prior to this Inspection standard.</li> <li>Viewing Judgement should be under static pattern.</li> <li>Inspection conditions         <ul> <li>Inspection distance : 250 mm (from the sample)</li> <li>Temperature : 25±5 °C</li> <li>Inspection angle : 45degrees in LCD view direction</li> </ul> </li> </ol>			
Definitions of	Pinhole, Bright spot,The color of a small area is different from the			
Inspection items	Black spot, White spot, Black line, White Line, Foreign particle, Bubble	remainder. The phenomenon dose not change with voltage.		
	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage.		
	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass.		
	Glass defect	Glass crack, Shaved corner of glass, Surplus glass		
Definitions of Inspection ranges	X1X2 $\rightarrow$ $\leftarrow$ Dividing A zone and B zone proceed to make $\rightarrow$ $\leftarrow$ $\downarrow$ $\rightarrow$ $\leftarrow$ $\downarrow$ $\downarrow$ $\downarrow$ $\downarrow$ $\downarrow$ $\uparrow$ $\downarrow$			
Outgoing		nal Inspection Sampling standard con		
Inspection Rank Inspection Item standard		AQL(Number of defective LCMs counted)		
	defect abnormally, O circuit, Missin	lefect abnormally, Open or missing segment, Short circuit, Missing component, No sound, Blight abnormally),Outline dimension beyond the		
	MinorAppearance defects, such as Black/White spot, Bright spot, Pinhole, Black/White line, Contrast variation, Bubble Glass defect, and so on. Details of the standard as follows.1.50			



# 8.2Standards of inspection items

		Judgement standard				
Inspection item				Acceptable number		
			Category	A zone	B zone	
1	Black spot, White spot Bright Spot, Pinhole Foreign P Bubble and Particle Between polarizer	$\Phi = (a+b)/2(mm)$ and glass,	A B C D	$\Phi \leq 0.15$ $0.15 < \Phi \leq 0.20$ $0.20 < \Phi \leq 0.30$ $0.30 < \Phi$ Total defective point(B,C)	Neglecte 2 1 0 3	Neglected
2	Scratch on polariz Black line, White line, Bubble and Particle Between Polarizer and glass, Scratch on polarizer	W:Width, L:Length(mm)	A B C D	W         0.10           0.01 <w< td="">         0.03         L         3.0           0.03<w< td="">         0.05         L         3.0           0.05<w< td="">         Total defective point(B,C)</w<></w<></w<>	Neglected 2 1 0 2	Neglected
3	Contrast variation	$ \begin{array}{c c} & b \\ \hline \\ \hline \\ \hline \\ \hline \\ \hline \\ \Phi = (a+b)/2(mm) \end{array} $	A B C D	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Neglected 2 1 0 3	Neglected
4	Bubble inside cell		any	size	none	none
5	Polarizer defect (if Polarizer is used)	Scratch and damage on polarizer, Particle on polarizer or between polarizer and glass. Bubble, dent and convex	Refer to item 1 and item 2.A $\Phi$ 0.3NeglectedNeglectedB $0.3 < \Phi$ $0.7$ 2C $0.7 < \Phi$ 0Total defective point(B,C)2		Neglected	
6	Surplus glass	①Stage surplus glass b ②Surrounding surplus glass		0.3mm ould not influence outline dime	nsion and as	sembling.



		Inspection item	Judgment standard		
			Category(application: B zone)		
7	Glass ①The front of lead terminals defect crack b		A       If       a       t and b       1.0,       c is not         limited		
		w t a c	b 0.5mm. D Crack at two sids of lead terminals should not cover patterns and alignment mark		
		②Surrounding crack—non-contact side          seal       b       a       t         c       b       a       t         Inner border line of the seal       Outer border line of the seal	b < Inner borderline of the seal		
		3 Surrounding crack— contact side seal c b a Inner border line of the seal Outer border line of the seal	b < Outer borderline of the seal		
		④Corner       W     A       W     C	A a t, b 3.0, c 3.0 *Glass crack should not cover patterns used for		



Inspection item			Judgement standard	
8	PCB defectComponent soldering: No cold soldering, short, open circuit, burr, tin ball The flat encapsulation component position deviation must be less than 1/2 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)		Soldering pad Lead Component	
		lead defect: The lead lack must be less than 1/2of its width; The lead burr must be less than 1/2 of the seam; Impurities connect with the near leads is not permitted		
		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	head Base Board Soldering tin is not permit in this area	
			Base Board	



### 9. Precautions for Use of LCD Modules

#### **9.1 Handling Precautions**

- 9.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 9.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 9.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 9.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 9.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
  - Isopropyl alcohol
  - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- -Aromatic solvents
- 9.1.6 Do not attempt to disassemble the LCD Module.
- 9.1.7 If the logic circuit power is off, do not apply the input signals.
- 9.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
  - a. Be sure to ground the body when handling the LCD Modules.
  - b. Tools required for assembly, such as soldering irons, must be properly ground.

c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.



d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

#### 9.2 Storage precautions

- 9.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 9.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : $0 \,^{\circ} \mathbb{C} \sim 40 \,^{\circ} \mathbb{C}$ Relatively humidity: $\leq 80\%$ 

- 9.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- **9.3** The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.